



EECS 388: Embedded Systems, Spring 2023

Lecture 1

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About me

- Assistant Professor
 - University of Kansas
 - Co-director: ASTHA Labs



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Education and Work

- PhD: University of Florida, ECE, 2020
- MS: University of Toledo, EE, 2015
- BSc: Ahsanullah University of Sci. Tech., Bangladesh. 2012
- Work Experience:
 - Cisco Systems: Research Intern summer 2016 and 2017
 - University of Kansas, Asst. Professor, 2020 to present

What do we learn in EECS 388?

Theory

- Hardware/software architecture of embedded systems

Experiment

- Program a microprocessor to sense physical world and actuate upon

Overview of the topic



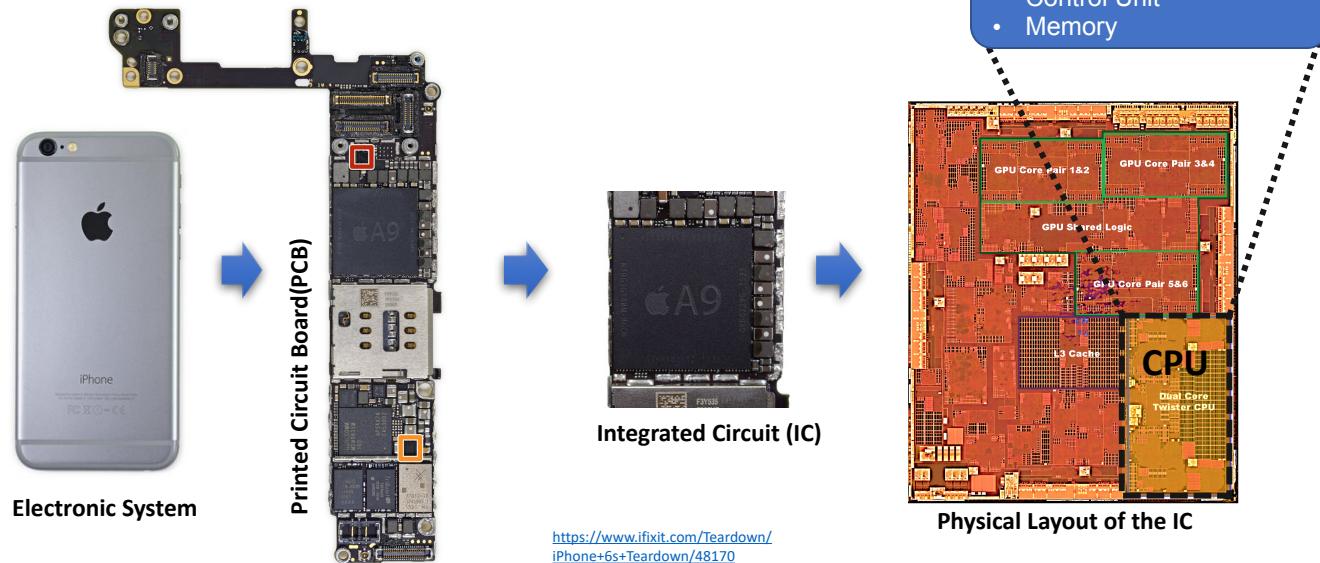
Embedded systems

Computers designed for specific purpose

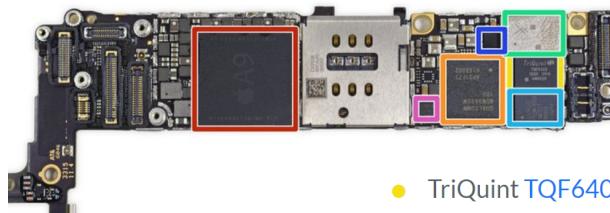


Breakdown of a Modern Embedded System

- Example: Apple iPhone



Breakdown of Modern Electronic System



- Apple A9 [APL1022](#) SoC + SK Hynix LPDDR4 RAM as denoted by the markings H9HKNNNBTUMUMR-NLH (we presume it is 2 GB LPDDR4 RAM, the same as in the iPhone 6s)
- Qualcomm [MDM9635M](#) LTE Cat. 6 Modem (vs. the [MDM9625M](#) found in the iPhone 6)
- TriQuint [TQF6405](#) Power Amplifier Module
- Skyworks [SKY77812](#) Power Amplifier Module
- Avago [AFEM-8030](#) Power Amplifier Module
- Qualcomm [QFE1100](#) Envelope Tracking IC
- Likely a InvenSense 6-axis gyroscope and accelerometer combo

<https://www.ifixit.com/Teardown/iPhone+6s+Plus+Teardown/48171>

Takeaway: Modern embedded systems contain a large number chips or integrated circuits (ICs)

Integrated Circuits: Types

Types: Digital, Analog, and Mixed Signals

Digital IC:

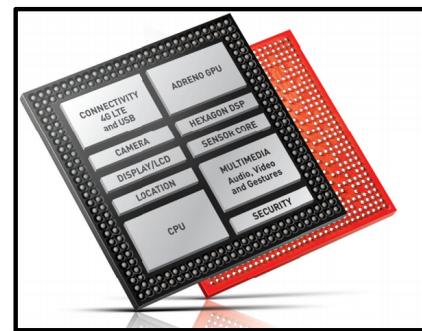
- Microprocessor
- Application Specific IC (ASIC)
- Field Programmable Gate Array (FPGA)
- Memory (SRAM, DRAM, Flash)

Analog IC:

- Sensors
- Power management circuits
- Operational amplifiers

Analog-mixed-signal (AMS):

Contains both digital and analog in a single chip/IC



Example: AMS IC

Internet of Things (IoT)

Internet connected embedded systems



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Cyber-Physical Systems (CPS)

- Cyber system (Computer) + Physical system (Plant)
- Embedded systems, but integration of physical system is emphasized



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Real-time systems

- The correctness of the system depends on not only on the logical result of the computation but also on the time at which the results are produced
- **A correct value at a wrong time is a fault.**
- CPS are often real-time systems
 - Because physical process depends on time



What makes
embedded
systems
different?

Embedded vs. general computing systems: Number of applications

Limited



Many



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Embedded vs. general computing systems: Programmability

Not end-user
programmable



End-user
programmable



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Embedded vs. general computing systems: Run-time constraints

On-time



Faster is
always better!



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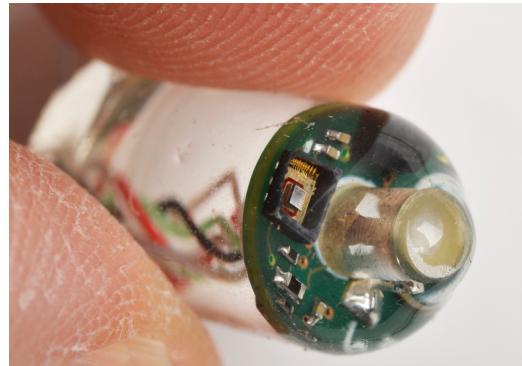
Embedded vs. general computing systems: Resource constraints

Power, memory,
& compute limited:

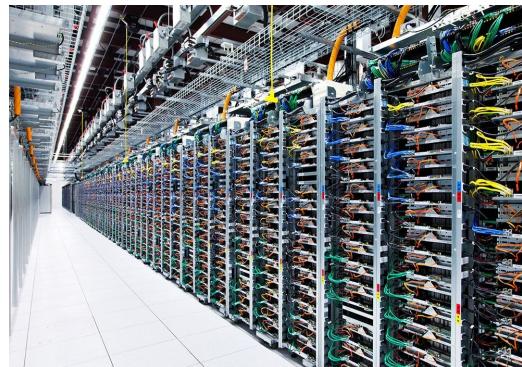
Ex: smart watch,
implantable healthcare
device

Greater resource!

Ex: servers



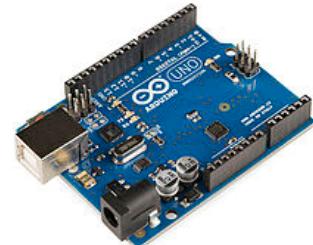
A Tiny Pill Monitors Vital Signs From Deep Inside The Body, NPR



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Trends in modern embedded systems

Trend: Cheaper, more powerful, and more connected computing



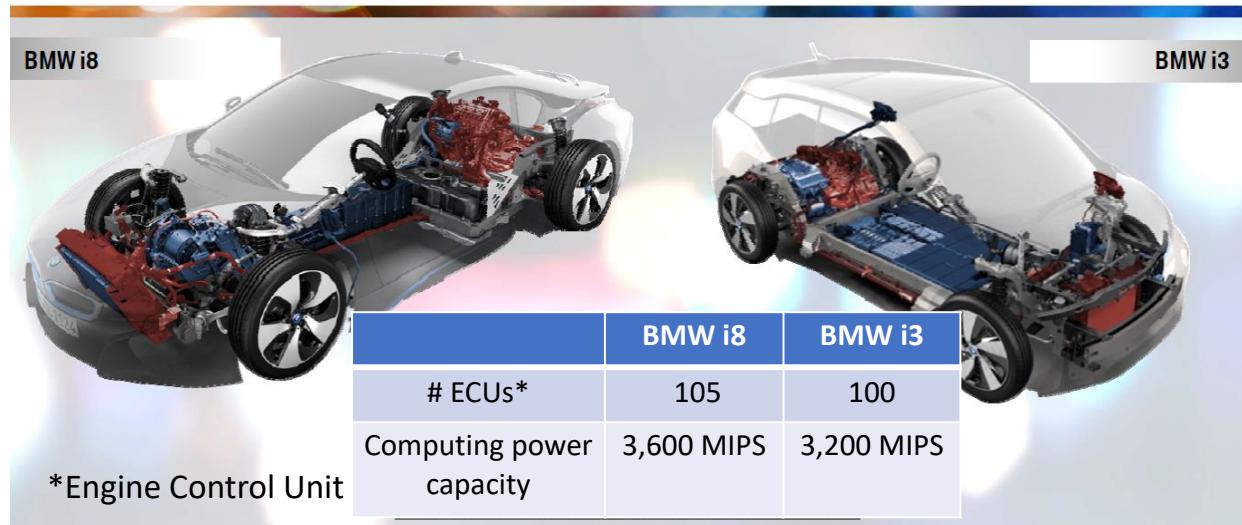
amazon echo

Always ready, connected, and fast. **Just ask.**



Trends in modern embedded systems

- The ECU computing capacity in BMW i8 is greater than i3.
- These computers were developed in 2014 or earlier.
- Raspberry pi 2 released in 2015 had even greater speed.
 - Compute power of a Raspberry Pi 2 is 4,744 MIPS at 1.0GHz!



Simon Fürst, BMW, EMCC2015 Munich, adopted from OSPERT2015 keynote

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Trends in modern embedded systems

Human-like intelligence needs for autonomous cars

- Sophisticated sensors and algorithms
- High-performance embedded computers



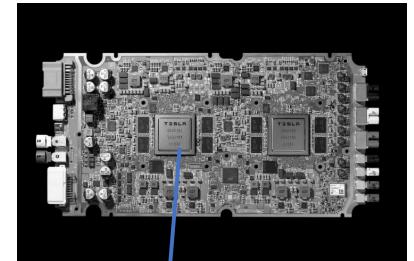
Semi autonomous car

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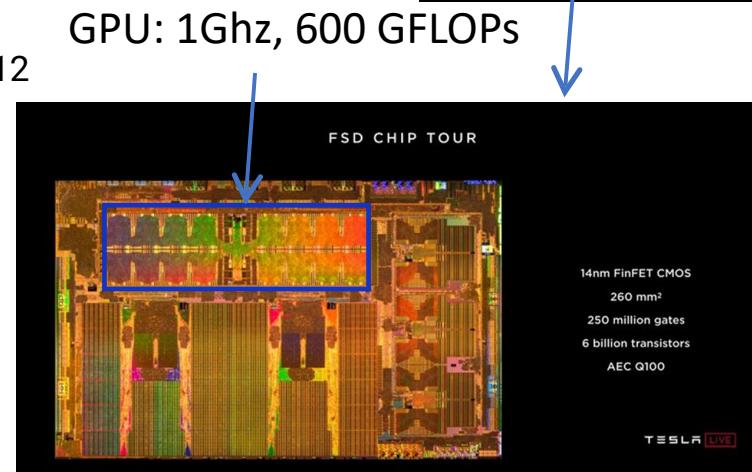
Trends in modern embedded systems

Super-computer on a car: Tesla FSD chip introduced in 2019

- Full Self-Driving Chip (FSD Chip, previously Autopilot Hardware 3.0)
- aimed at autonomous levels 4 and 5 (fully self driving).



- What's inside:
 - Incorporates 3 quad-core [Cortex-A72](#) clusters for a total of 12 CPUs operating at 2.2 GHz
 - GPU operating 1 GHz
 - 2 [neural processing units](#) operating at 2 GHz
 - various other hardware accelerators



FSD: Full Self-Driving Chip

GFLOPs: Gigaflop: one billion floating-point operations/sec.

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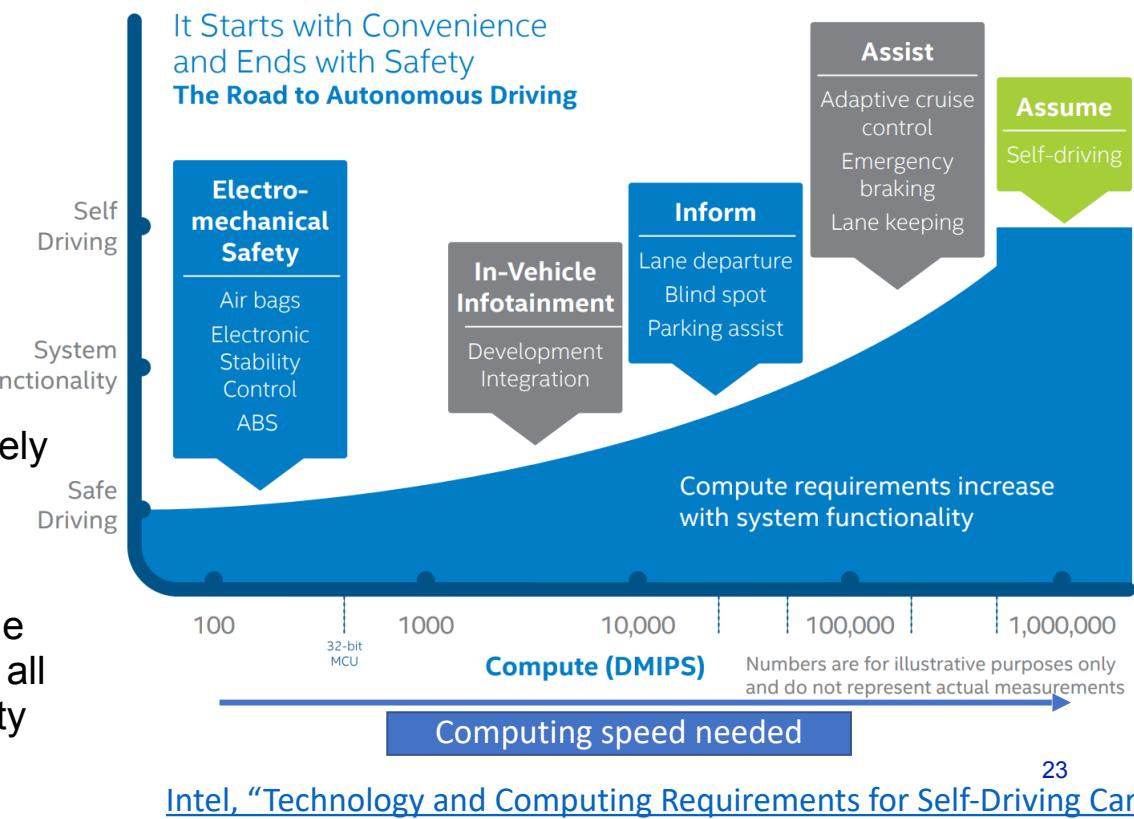
Requirements for CPS/IoT/Embedded Systems

1. Performance
2. Efficiency
3. Safety
4. Security and Privacy

Performance

Intel describes the trajectory of change in the automobile as a three-step process: “Inform, Assist, Assume.”

- **Inform:** Drivers wanted a way to seamlessly meld their connected lifestyle with their car.
- **Assist:** new capabilities that actively “assist” the driver.
- **Assume:** able to communicate, collaborate, and ultimately fulfill the human driving functions in almost all driving situations (e.g., parking, city driving, freeway driving).



Performance

Processing real-time data from many sensors requires powerful computers

- Approximately 1 GB of data will need to be processed each second in the car's real-time operating system.



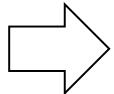
Source: <http://on-demand.gputechconf.com/gtc/2015/presentation/S5870-Daniel-Lipinski.pdf>

Efficiency

Size, weight, power and cost constraints



CMU's "Boss" Self-driving car, circa 2007
10 dual-processor blade servers on the trunk



Audi A8
Audi's zFAS platform. 2016-2018
A single-board computer with multiple
CPUs, GPU, FPGA

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Safety



Therac 25

- Computer controlled radiation therapy machine
- Six people died/injured due to massive overdoses (1985-1987)
- Caused by synchronization mistakes



Arian 5

- 7 billion dollar rocket was destroyed after 40 secs (6/4/1996)
- *“caused by the complete loss of guidance and altitude information”* → Caused by 64bit floating to 16bit integer conversion

<https://www.bugsnag.com/blog/bug-day-race-condition-therac-25>

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Security and Privacy

Confidentiality issues: Information could be stolen from the system.

Attack can be done in many ways:

1. **Side channel leakage:** observing the power consumption of the chip to guess the password.
2. **Hardware or software Trojan:** hidden functionality in software or hardware that leaks information (e.g., secret data) to outsider
3. **Physical attack:** Decapsulation and deprocessing of the chip to see what's inside (e.g., secret data)

Security and Privacy

Integrity issues: An attacker can initiate functional failure within the system

Attack can be done in many ways:

1. **Fault injection:** Causing a voltage glitch to corrupt the output of the chip
2. **Hardware or software Trojan:** hidden functionality in software or hardware that corrupts the output when the attacker activates the Trojan
3. **Physical attack and tampering:** mod chip attack on gaming console to bypass restrictions

Summary

Embedded systems, cyber-physical systems, real-time systems, IoT

- Limited function computers integrated into physical world
- Requirements: performance, efficiency, safety, security, and privacy

In this course we learn concepts and skills for developing embedded systems

Future Job Prospect in Semiconductor Industry



New Chip-factory in Ohio

- “Intel will invest more than \$20 billion ... for advanced chipmaking in the Midwest.”
- Expected to create 3,000 Intel jobs
- “Could grow to as much as \$100 billion over the next decade, making it one of the largest semiconductor manufacturing sites in the world”

- Source: [Link](#)



The CHIPS and Science Act

- US is dependent on a globalized supply chain for chip design
- President Joe Biden recently signed a law to aid the U.S. chip industry
- \$52.7 billion for research and development and domestic manufacturing of semiconductors

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Instructor and GTAs



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Course Structure

- Lecture (in-person)
 - Focus on key concepts
- Homework, In class quiz, exams
- Lab (in-person)
 - Hands-on embedded systems programming experiences

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Tentative Grading

- Homework: 10%
- In class quiz: 5%
- Midterm: 20%
- Final: 25%
- Lab: 40%
 - (*Weekly labs 25% + final project: 15%*)
- **Grading Scale**

| A | A- | B+ | B | B- | C+ | C | C- | D+ | D | D- | F |
|------|---------|---------|---------|---------|---------|---------|---------|---------|---------|---------|-----|
| 93<= | [89-93) | [86-89) | [83-86) | [79-83) | [76-79) | [73-76) | [69-73) | [66-69) | [63-66) | [59-63) | <59 |

Lecture Recording

- I will try to record it, but there is no guarantee for all lectures to be available/recorded correctly.
 - Don't count on recording and miss the classes
 - Use it for reviewing before the exam
- Absence in the class may lead to missing in class quizzes

Please do not cheat,
and lets enjoy the course together

Syllabus will be uploaded today with detailed
course policies